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Index of products and services

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3 Electronics assembly and packaging, system integration

- 3.1 Electronics assembly and packaging
 - 3.1.1 Flip chip
 - 3.1.2 Other electrical contacting
- 3.2 Lamination
- 3.3 System integration
- 3.4 Hybrid systems (polytronics)

4 Inspection and test systems

- 4.1 Electrical characterization
- 4.2 Physical/optical characterization
- 4.3 Chemical characterization
- 4.4 Simulation/circuit optimization
- 4.5 Lifetime testing
- 4.6 Quality/process control
- 4.7 Environmental testing
- 4.8 Other inspection and test systems

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 - 5.3.1 Capacitors
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 - 5.6.3 Inorganic photovoltaics

5.7 Sensors

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- 5.7.3 Temperature sensors
- 5.7.4 Biomedical sensors
- 5.7.5 Gas sensors
- 5.7.6 Touch sensors
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- 6.3 Sensors
- 6.4 Smart systems
- 6.5 RFID
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- 6.7 Smart textiles
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- 7.3 R&D/Research & Development
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- 7.7 Professional and trade associations
- 7.8 Technical books, technical journals, technical publishers
- 7.9 Other services